

HD6802

MPU (Microprocessor with Clock and RAM)

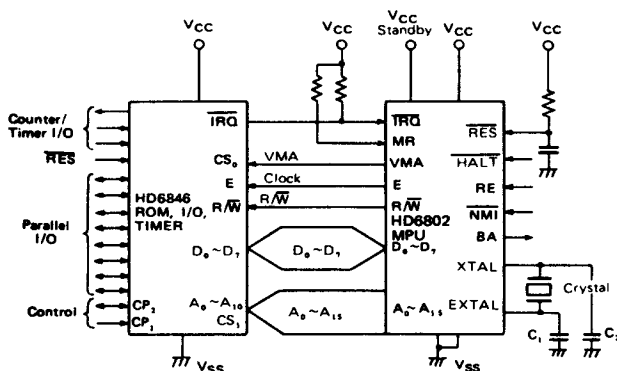
The HD6802 is a monolithic 8-bit microprocessor that contains all the registers and accumulators of the present HD6800 plus an internal clock oscillator and driver on the same chip. In addition, the HD6802 has 128 bytes of RAM on the chip located at hex addresses 0000 to 007F. The first 32 bytes of RAM, at hex addresses 0000 to 001F, may be retained in a low power mode by utilizing V_{CC} standby, thus facilitating memory retention during a power-down situation.

The HD6802 is completely software compatible with the HD6800 as well as the entire HMCS6800 family of parts. Hence, the HD6802 is expandable to 65k words.

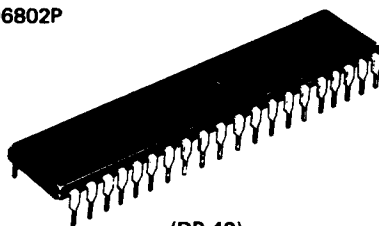
■ FEATURES

- On-Chip Clock Circuit
- 128×8 Bit On-Chip RAM
- 32 Bytes of RAM are Retainable
- Software-Compatible with the HD6800
- Expandable to 65k words
- Standard TTL-Compatible Inputs and Outputs
- 8 Bit Word Size
- 16 Bit Memory Addressing
- Interrupt Capability
- Compatible with MC6802

■ BLOCK DIAGRAM

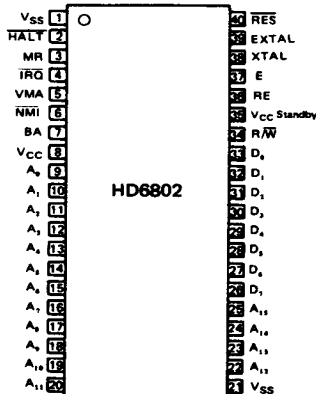


HD6802P



(DP-40)

■ PIN ARRANGEMENT



(Top View)



■ ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Value	Unit
Supply Voltage	V_{CC}^* $V_{CC} \text{ Standby}^*$	-0.3 ~ +7.0	V
Input Voltage	V_{in}^*	-0.3 ~ +7.0	V
Operating Temperature	T_{opr}	-20 ~ +75	°C
Storage Temperature	T_{stg}	-55 ~ +150	°C

* With respect to V_{SS} (SYSTEM GND)

(NOTE) Permanent LSI damage may occur if maximum ratings are exceeded. Normal operation should be under recommended operating conditions. If these conditions are exceeded, it could affect reliability of LSI.

■ RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
Supply Voltage	V_{CC}^* $V_{CC} \text{ Standby}^*$	4.75	5.0	5.25	V
Input Voltage	V_{IL}^*	-0.3	—	0.8	V
	V_{IH}^*	Except RES	2.0	—	V_{CC} V
		RES	4.25	—	V_{CC} V
Operation Temperature	T_{opr}	-20	25	75	°C

* With respect to V_{SS} (SYSTEM GND)

■ ELECTRICAL CHARACTERISTICS

● DC CHARACTERISTICS ($V_{CC}=5.0V \pm 5\%$, $V_{CC} \text{ Standby}=5.0V \pm 5\%$, $V_{SS}=0V$, $T_a=-20 \sim +75^\circ\text{C}$, unless otherwise noted.)

Item		Symbol	Test Condition	min	typ**	max	Unit
Input "High" Voltage	Except RES	V_{IH}		2.0	—	V_{CC}	V
	RES			4.25	—	V_{CC}	
Input "Low" Voltage	Except RES	V_{IL}		-0.3	—	0.8	V
	RES			-0.3	—	0.8	
Output "High" Voltage	$D_0 \sim D_7, E$	V_{OH}	$I_{OH} = -205\mu A$	2.4	—	—	V
	$A_0 \sim A_{15}, R/\overline{W}, VMA$		$I_{OH} = -145\mu A$	2.4	—	—	
	BA		$I_{OH} = -100\mu A$	2.4	—	—	
Output "Low" Voltage		V_{OL}	$I_{OL} = 1.6mA$	—	—	0.4	V
Three State (Off State) Input Current	$D_0 \sim D_7$	I_{TSI}	$V_{in} = 0.4 \sim 2.4V$	-10	—	10	μA
Input Leakage Current	Except $D_0 \sim D_7$ ****	I_{in}	$V_{in} = 0 \sim 5.25V$	-2.5	—	2.5	μA
Power Dissipation		P_D^*		—	0.6	1.2	W
Input Capacitance	$D_0 \sim D_7$	C_{in}	$V_{in}=0V, T_a=25^\circ C,$ $f=1.0MHz$	—	10	12.5	pF
	Except $D_0 \sim D_7$			—	6.5	10	
Output Capacitance	$A_0 \sim A_{15}, R/\overline{W}, BA,$ VMA, E	C_{out}	$V_{in}=0V, T_a=25^\circ C,$ $f=1.0MHz$	—	—	12	pF

* In power-down mode, maximum power dissipation is less than 42mW.

** $T_a=25^\circ\text{C}$, $V_{CC}=5V$

*** As RES input has hysteresis character, applied voltage up to 2.4V is regarded as "Low" level when it goes up from 0V.

**** Does not include EXTAL and XTAL, which are crystal inputs.



• AC CHARACTERISTICS ($V_{CC}=5.0V\pm5\%$, V_{CC} Standby= $5.0V\pm5\%$, $V_{SS}=0V$, $T_a=-20\sim+75^\circ C$, unless otherwise noted.)

1. CLOCK TIMING CHARACTERISTICS

Item	Symbol	Test Condition	min	typ	max	Unit
Frequency of Operation	Input Clock $\div 4$	f	0.1	—	1.0	MHz
	Crystal Frequency	f_{XTAL}	1.0	—	4.0	
Cycle Time	t_{cyc}	Fig. 2, Fig. 3	1.0	—	10	μs
Clock Pulse Width	"High" Level	$PW_{\phi H}$ at 2.4V (Fig. 2, Fig. 3)	450	—	4500	ns
	"Low" Level	$PW_{\phi L}$ at 0.4V (Fig. 2, Fig. 3)	—	—	—	
Clock Fall Time	t_{ϕ}	0.4V $\sim$ 2.4V (Fig. 2, Fig. 3)	—	—	25	ns

2. READ/WRITE TIMING

Item	Symbol	Test Condition	min	typ*	max	Unit
Address Delay	t_{AD}	Fig. 2, Fig. 3, Fig. 6	—	—	270	ns
Peripheral Read Access Time	t_{RAC}	Fig. 2	530	—	—	ns
Data Setup Time (Read)	t_{DSR}	Fig. 2	100	—	—	ns
Input Data Hold Time	t_H	Fig. 2	10	—	—	ns
Output Data Hold Time	t_H	Fig. 3	20	—	—	ns
Address Hold Time (Address, $R/\bar{W}$, VMA)	t_{AH}	Fig. 2, Fig. 3	10	—	—	ns
Data Delay Time (Write)	t_{DDW}	Fig. 3	—	—	225	ns
Bus Available Delay	t_{BA}	Fig. 4, Fig. 5, Fig. 7, Fig. 8	—	—	250	ns
Processor Controls Processor Control Setup Time Processor Control Rise and Fall Time (Measured at 0.8V and 2.0V)	t_{PCS}	Fig. 4~Fig. 7, Fig. 12	200	—	—	ns
	t_{PCr}	Fig. 4~Fig. 7, Fig. 12, Fig. 13, Fig. 16	—	—	100	ns
	t_{PCf}					

* $T_a = 25^\circ C$, $V_{CC} = 5V$

3. POWER DOWN SEQUENCE TIMING, POWER UP RESET TIMING AND MEMORY READY TIMING

Item	Symbol	Test Condition	min	typ	max	Unit
RAM Enable Reset Time (1)	t_{RE1}	Fig. 13	150	—	—	ns
RAM Enable Reset Time (2)	t_{RE2}	Fig. 13	E-3 cycles	—	—	—
Reset Release Time	t_{LRES}	Fig. 12	20*	—	—	ms
RAM Enable Reset Time (3)	t_{RE3}	Fig. 12	0	—	—	ns
Memory Ready Setup Time	t_{SMR}	Fig. 16	300	—	—	ns
Memory Ready Hold Time	t_{HMR}	Fig. 16	0	—	200	ns

* $t_{RES} = 20$ msec min. for S type, 50 msec min. for R type.



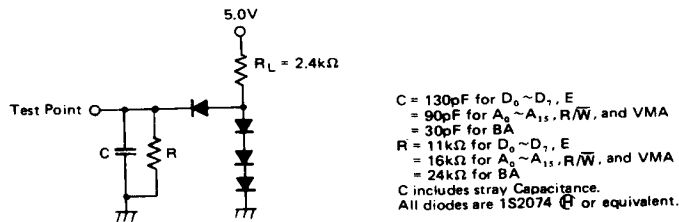


Figure 1 Bus Timing Test Load

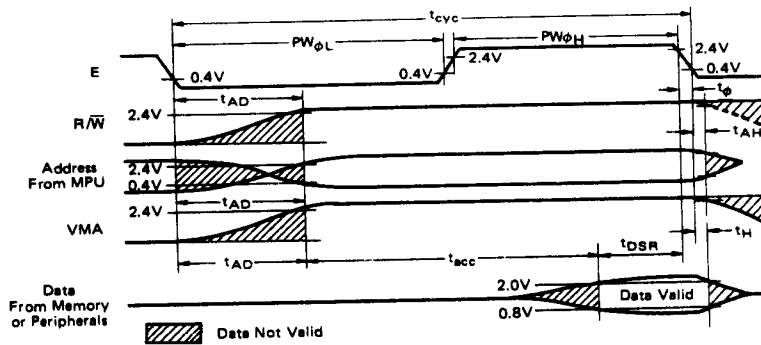


Figure 2 Read Data from Memory or Peripherals

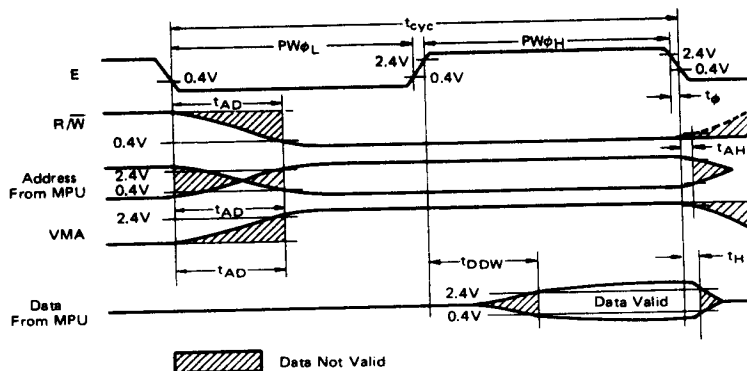
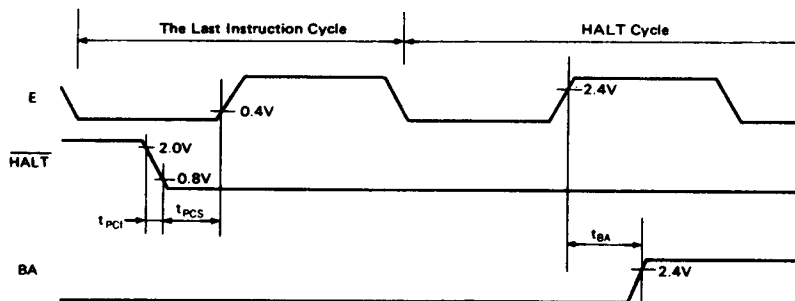
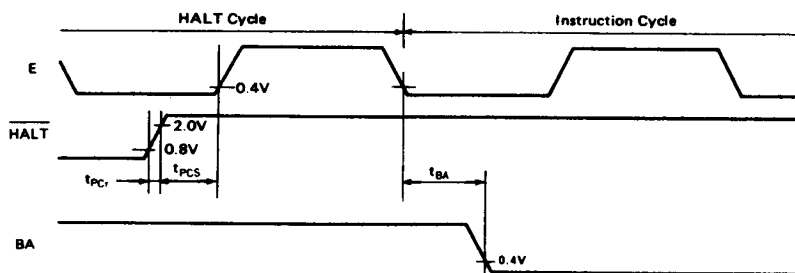
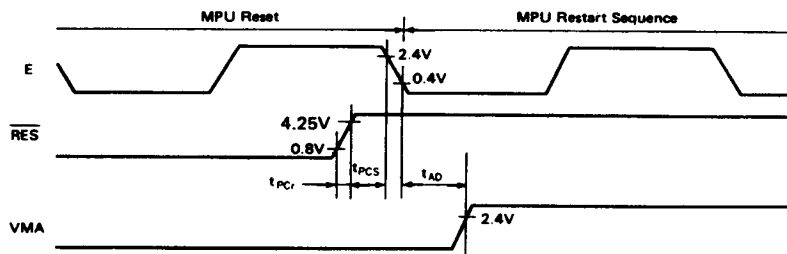


Figure 3 Write Data in Memory or Peripherals



Figure 4 Timing of $\overline{\text{HALT}}$ and BAFigure 5 Timing of $\overline{\text{HALT}}$ and BAFigure 6 $\overline{\text{RES}}$ and MPU Restart Sequence

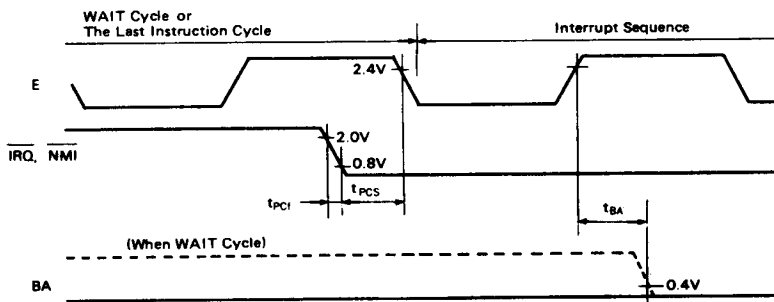
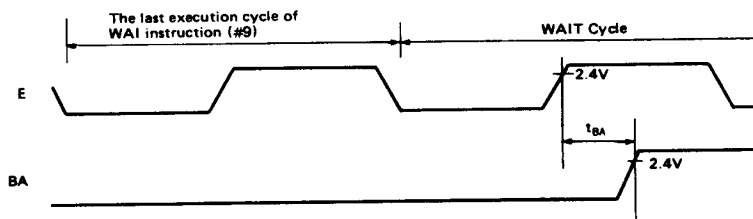
Figure 7 $\overline{\text{IRQ}}$ and $\overline{\text{NMI}}$ Interrupt Timing

Figure 8 WAI Instruction and BA Timing

■ MPU REGISTERS

A general block diagram of the HD6802 is shown in Fig. 9. As shown, the number and configuration of the registers are the same as for the HD6800. The 128 × 8 bit RAM has been added to the basic MPU. The first 32 bytes may be operated in a low power mode via a V_{CC} standby. These 32 bytes can be retained during power-up and power-down conditions via the RE signal.

The MPU has three 16-bit registers and three 8-bit registers available for use by the programmer (Fig. 10).

● Program Counter (PC)

The program counter is a two byte (16-bit) register that points to the current program address.

● Stack Pointer (SP)

The stack pointer is a two byte (16-bit) register that contains the address of the next available location in an external push-down/pop-up stack. This stack is normally a random access Read/Write memory that may have any location (address) that is convenient. In those applications that require storage of information in the stack when power is lost, the stack must be non-volatile.

● Index Register (IX)

The index register is a two byte register that is used to store data or a sixteen bit memory address for the Indexed mode of memory addressing.

● Accumulators (ACCA, ACCB)

The MPU contains two 8-bit accumulators that are used to hold operands and results from an arithmetic logic unit (ALU).

● Condition Code Register (CCR)

The condition code register indicates the results of an Arithmetic Logic Unit operation: Negative(N), Zero(Z), Overflow(V), Carry from bit7(C), and half carry from bit3(H). These bits of the Condition Code Register are used as testable conditions for the conditional branch instructions. Bit 4 is the interrupt mask bit(I). The used bits of the Condition Code Register (B6 and B7) are ones.

Fig. 11 shows the order of saving the microprocessor status within the stack.

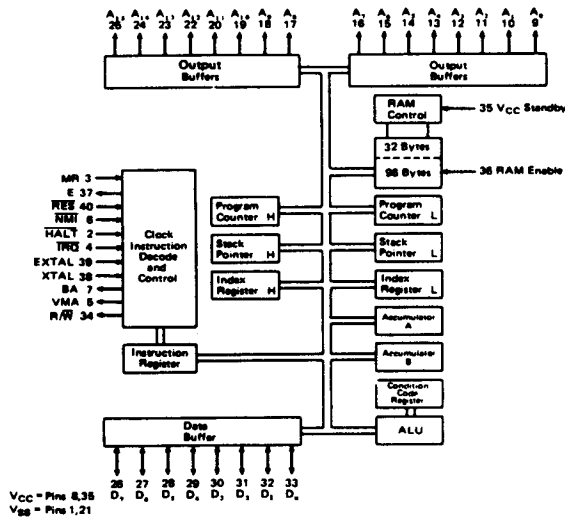


Figure 9 Expanded Block Diagram

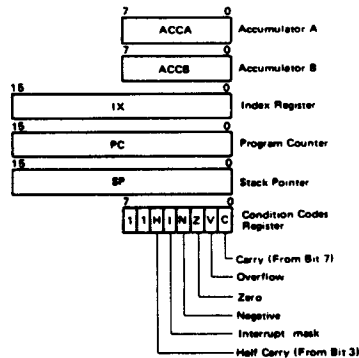


Figure 10 Programming Model of The Microprocessing Unit

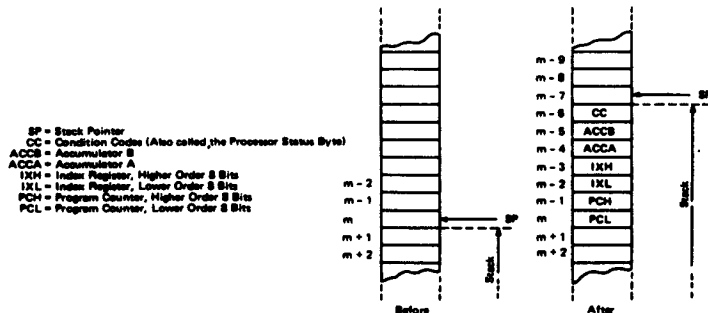


Figure 11 Saving The Status of The Microprocessor in The Stack



■ HD6802 MPU SIGNAL DESCRIPTION

Proper operation of the MPU requires that certain control and timing signals be provided to accomplish specific functions and that other signal lines be monitored to determine the state of the processor. These control and timing signals for the HD6802 are similar to those of the HD6800 except that TSC, DBE, ϕ_1 , ϕ_2 input, and two unused pins have been eliminated, and the following signal and timing lines have been added.

RAM Enable (RE)
Crystal Connections EXTAL and XTAL
Memory Ready(MR)
V_{CC} Standby
Enable ϕ_2 Output(E)

The following is a summary of the HD6802 MPU signals:

● Address Bus (A₀ ~ A₁₅)

Sixteen pins are used for the address bus. The outputs are capable of driving one standard TTL load and 90pF.

● Data Bus (D₀ ~ D₇)

Eight pins are used for the data bus. It is bidirectional, transferring data to and from the memory and peripheral devices. It also has three-state output buffers capable of driving one standard TTL load and 130pF.

Data Bus will be in the output mode when the internal RAM is accessed. This prohibits external data entering the MPU. It should be noted that the internal RAM is fully decoded from \$0000 to \$007F. External RAM at \$0000 to \$007F must be disabled when internal RAM is accessed.

● HALT

When this input is in the "Low" state, all activity in the machine will be halted: This input is level sensitive.

In the halt mode, the machine will stop at the end of an instruction. Bus Available will be at a "High" state. Valid Memory Address will be at a "Low" state. The address bus will display the address of the next instruction.

To insure single instruction operation, transition of the HALT line must not occur during the last 250ns of E and the HALT line must go "High" for one Clock cycle.

HALT should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

● Read/Write (R/W)

This TTL compatible output signals the peripherals and memory devices whether the MPU is in a Read ("High") or Write ("Low") state. The normal standby state of this signal is Read ("High"). When the processor is halted, it will be in the logical one state ("High").

This output is capable of driving one standard TTL load and 90pF.

● Valid Memory Address (VMA)

This output indicates to peripheral devices that there is a valid address on the address bus. In normal operation, this signal should be utilized for enabling peripheral interfaces such as the PIA and ACIA. This signal is not three-state. One standard TTL load and 90pF may be directly driven by this active high signal.

● Bus Available (BA)

The Bus Available signal will normally be in the "Low" state. When activated, it will go to the "High" state indicating that the microprocessor has stopped and that the address bus is available (but not in a three-state condition). This will occur if the HALT line is in the "Low" state or the processor is in the wait state as a result of the execution of a WAI instruction. At such time, all three-state output drivers will go to their off state and other

outputs to their normally inactive level.

The processor is removed from the wait state by the occurrence of a maskable (mask bit I=0) or nonmaskable interrupt. This output is capable of driving one standard TTL load and 30pF.

● Interrupt Request (IRQ)

This level sensitive input requests that an interrupt sequence be generated within the machine. The processor will wait, until it completes the current instruction that is being executed before it recognizes the request. At that time, if the interrupt mask bit in the Condition Code Register is not set, the machine will begin an interrupt sequence. The index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. Next the MPU will respond to the interrupt request by setting the interrupt mask bit high so that no further interrupts may occur. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFF8 and FFF9. An address loaded at these locations causes the MPU to branch to an interrupt routine in memory.

The HALT line must be in the "High" state for interrupts to be serviced. Interrupts will be latched internally while HALT is "Low".

A 3k Ω external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

● Reset (RES)

This input is used to reset and start the MPU from a power-down condition, resulting from a power failure or an initial start-up of the processor. When this line is "Low", the MPU is inactive and the information in the registers will be lost. If a "High" level is detected on the input, this will signal the MPU to begin the restart sequence. This will start execution of a routine to initialize the processor from its reset condition. All the higher order address lines will be forced "High". For the restart, the last two(FFFE, FFFF) locations in memory will be used to load the program that is addressed by the program counter. During the restart routine, the interrupt mask bit is set and must be reset before the MPU can be interrupted by IRQ. Power-up and reset timing and power-down sequences are shown in Fig. 12 and Fig. 13 respectively.

● Non-Maskable Interrupt (NMI)

A low-going edge on this input requests that a non-mask-interrupt sequence be generated within the processor. As with the IRQ signal, the processor will complete the current instruction that is being executed before it recognizes the NMI signal. The interrupt mask bit in the Condition Code Register has no effect on NMI.

The Index Register, Program Counter, Accumulators, and Condition Code Register are stored away on the stack. At the end of the cycle, a 16-bit address will be loaded that points to a vectoring address which is located in memory locations FFFC and FFFD. An address loaded at these locations causes the MPU to branch to a non-maskable interrupt routine in memory. A 3k Ω external resistor to V_{CC} should be used for wire-OR and optimum control of interrupts.

Inputs IRQ and NMI are hardware interrupt lines that are sampled when E is "High" and will start the interrupt routine on a "Low" E following the completion of an instruction. IRQ and NMI should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. Fig. 14 is a flowchart describing the major decision paths and interrupt vectors of the microprocessor. Table 1 gives the memory map for interrupt vectors.



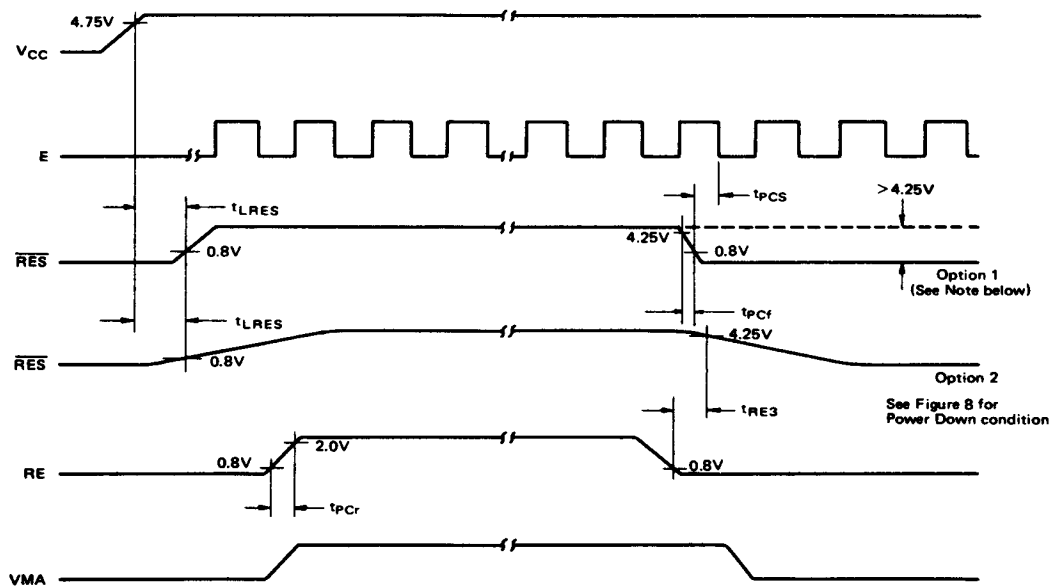


Figure 12 Power-up and Reset Timing

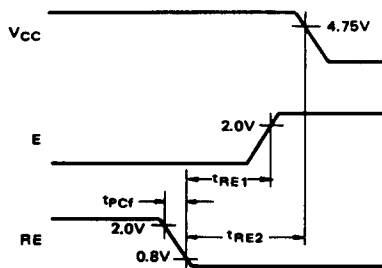


Figure 13 Power-down Sequence

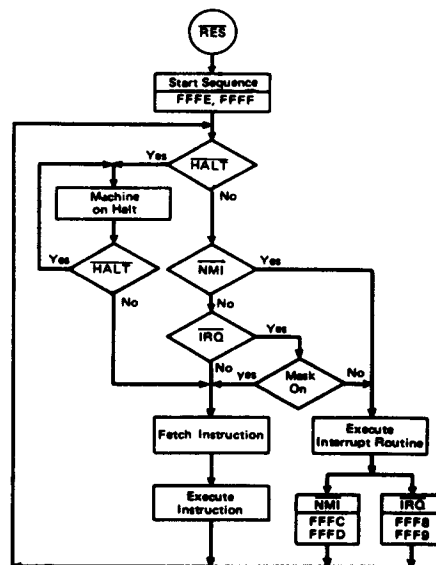


Figure 14 MPU Flow Chart



Table 1 Memory Map for Interrupt Vectors

MS	Vector	LS	Description
FFFE	FFFF		Restart (RES)
FFFC	FFFD		Non-Maskable Interrupt (NMI)
FFFA	FFFB		Software Interrupt (SWI)
FFF8	FFF9		Interrupt Request (IRQ)

• RAM Enable (RE)

A TTL-compatible RAM enable input controls the on-chip RAM of the HD6802. When placed in the "High" state, the on-chip memory is enabled to respond to the MPU controls. In the "Low" state, RAM is disabled. This pin may also be utilized to disable reading and writing the on-chip RAM during a power-down situation. RAM enable must be "Low" three cycles before V_{CC} goes below 4.75V during power-down.

RE should be tied to the correct "High" or "Low" state if not used. This is good engineering design practice in general and necessary to insure proper operation of the part.

• EXTAL and XTAL

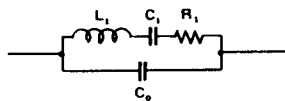
The HD6802 has an internal oscillator that may be crystal controlled. These connections are for a parallel resonant fundamental crystal (AT cut). A divide-by-four circuit has been added to the HD6802 so that a 4MHz crystal may be used in lieu of a 1MHz crystal for a more cost-effective system. Pin39 of the HD6802 may be driven externally by a TTL input signal if a separate clock is required. Pin38 is to be left open in this mode.

An RC network is not directly usable as a frequency source on pins 38 and 39. An RC network type TTL or CMOS oscillator will work well as long as the TTL or CMOS output drives the HD6802.

If an external clock is used, it may not be halted for more than $4.5\mu s$. The HD6802 is a dynamic part except for the internal RAM, and requires the external clock to retain information.

Conditions for Crystal (4 MHz)

- AT Cut Parallel resonant
- $C_0 = 7 \text{ pF max.}$
- $R_1 = 80\Omega \text{ max.}$



Crystal Equivalent Circuit

Recommended Oscillator (4MHz)

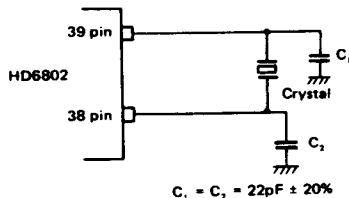


Figure 15 Crystal Oscillator

When using the crystal, see the note for Board Design of the Oscillation Circuit in HD6802.

• Memory Ready (MR)

MR is a TTL compatible input control signal which allows stretching of E. When MR is "High", E will be in normal operation. When MR is "Low", E may be stretched integral multiples of half periods, thus allowing interface to slow memories. Memory Ready timing is shown in Fig. 16.

MR should be tied "High" if not used. This is good engineering design practice in general and necessary to insure proper operation of the part. A maximum stretch is $4.5\mu s$.

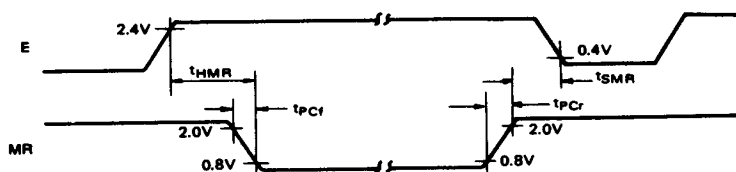


Figure 16 Memory Ready Control Function



- **Enable (E)**

This pin supplies the clock for the MPU and the rest of the system. This is a single phase, TTL compatible clock. This clock may be conditioned by a Memory Ready Signal. This is equivalent to ϕ_2 on the HD6800.

- **V_{CC} Standby**

This pin supplies the dc voltage to the first 32 bytes of RAM as well as the RAM Enable (RE) control logic. Thus retention of data in this portion of the RAM on a power up, power-down, or standby condition is guaranteed at the range of 4.0 V to 5.25 V. Maximum current drain at 5.25V is 8mA.

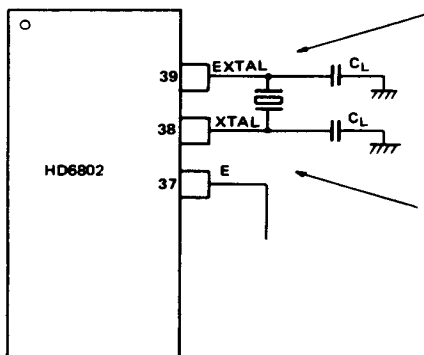
- **MPU INSTRUCTION SET**

The HD6802 has a set of 72 different instructions. Included are binary and decimal arithmetic, logical, shift, rotate, load, store, conditional or unconditional branch, interrupt and stack manipulation instructions.

This instruction set is the same as that for the 6800MPU (HD6800 etc.) and is not explained again in this data sheet.

- **NOTE FOR BOARD DESIGN OF THE OSCILLATION CIRCUIT IN HD6802**

In designing the board, the following notes should be taken when the crystal oscillator is used.

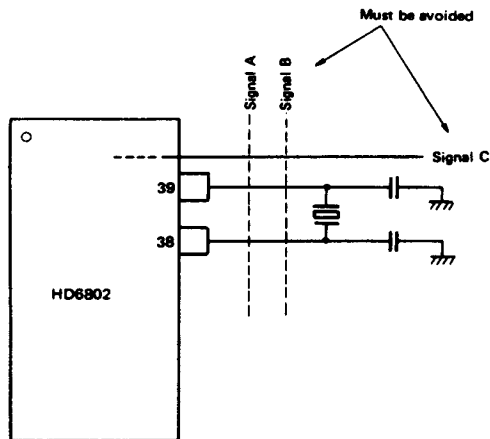


Crystal oscillator and load capacity C_L must be placed near the LSI as much as possible.

Normal oscillation may be disturbed when external noise is induced to pin 38 and 39.

Pin 38 signal line should be wired apart from pin 37 signal line as much as possible. Don't wire them in parallel, or normal oscillation may be disturbed when E signal is feedbacked to XTAL.

The following design must be avoided.



A signal line or a power source line must not cross or go near the oscillation circuit line as shown in the left figure to prevent the induction from these lines and perform the correct oscillation. The resistance among XTAL, EXTAL and other pins should be over 10M Ω .

Figure 17 Note for Board Design of the Oscillation Circuit



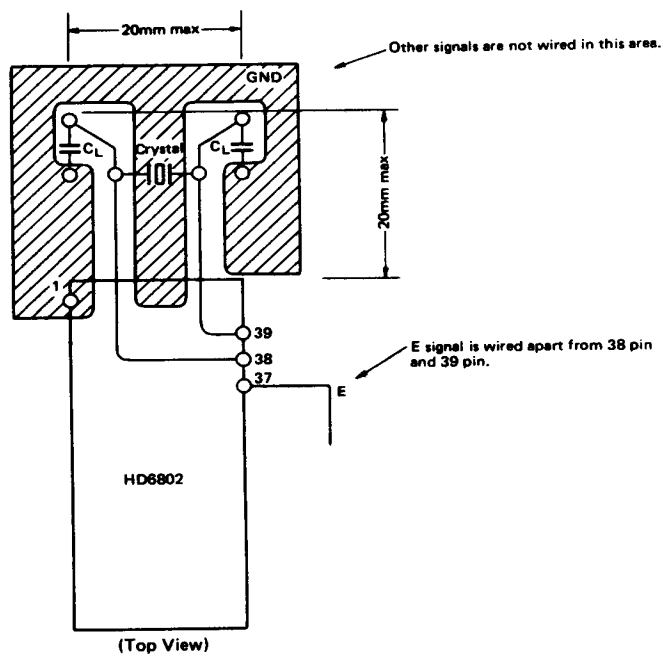


Figure 18 Example of Board Design Using the Crystal Oscillator

■ NOTE FOR THE RELATION BETWEEN WAI INSTRUCTION AND HALT OPERATION OF HD6802

When $\overline{\text{HALT}}$ input signal is asserted to "Low" level, the MPU will be halted after the execution of the current instruction except WAI instruction.

The "Halt" signal is not accepted after the fetch cycle of the WAI instruction (See ① in Fig. 19). In the case of the "WAI" instruction, the MPU enters the "WAIT" cycle after stacking the internal registers and

outputs the "High" level on the BA line.

When an interrupt request signal is input to the MPU, the MPU accepts the interrupt regardless the "Halt" signal and releases the "WAIT" state and outputs the interrupt's vector address. If the "Halt" signal is "Low" level, the MPU halts after the fetch of new PC contents. The sequence is shown below.

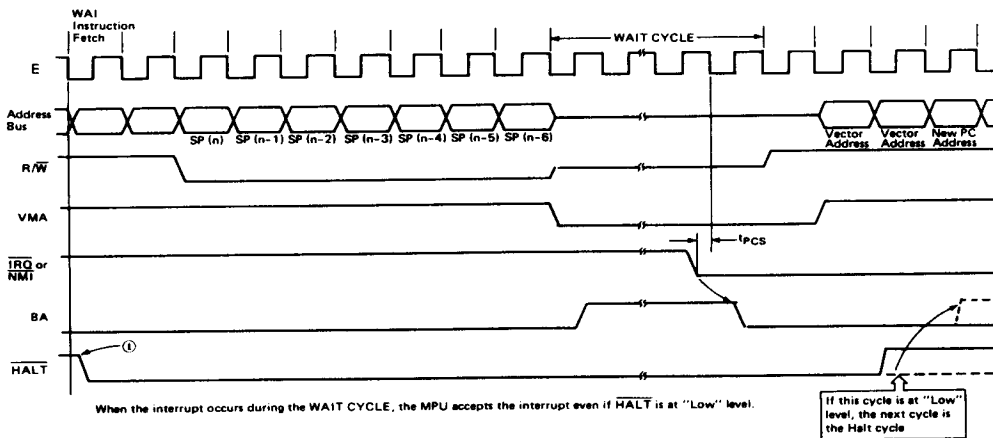


Figure 19 HD6802 WAIT CYCLE & $\overline{\text{HALT}}$ Request

